ABSTRACT

A new method is provided for mounting a semiconductor on the surface of a Printed Circuit Board. A layer of Elastomer is deposited on the surface of the PCB, this layer of Elastomer makes the PCB into a thermally compliant PCB such that the thermal mismatch between the PCB and the semiconductor die that is mounted on the PCB is sharply reduced. Openings are created in the layer of Elastomer and electrical interfaces are created such that the PCB can be connected to the semiconductor die that is mounted on the PCB.